06-11-1999



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To the Honorable Commissioner of Patents and Trademarks. Please	record the attached original documents or copy thereof
Name of conveying party(ies):	Name and address of receiving party(ies):
(a) Horii, Hideki	Name: Samsung Electronics Co., Ltd.
(b)	Internal Address:
(c)	
Additional name(s) of conveying party(ies) attached?	
☐ Yes No	Street Address: 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-
	do, Republic of Korea
3. Nature of Conveyance:	do, Republic of Rolea
	City State ZIP
Assignment Merger	Only Orace 211
Security Agreement Change of Name	Additional name(s) & address(es) attached?
Other	
Execution Date: April 13, 1999	
Application number(s) or patent number(s): If this document is being filed together with a new application,	the execution date of the application is: April 13, 1999
A. Patent Application No.(s) -	B. Patent No.(s)
Title: Capacitor Having Electrode Formed By Electroplating	09333600
And Manufacturing Method Thereof	0 (3 % 3000
Additional number	rs attached?
Name and address of party to whom correspondence concerning document should be mailed:	Total number of applications and patents involved:
Name: David T. Millers	
Internal Address: SKJERVEN, MORRILL, MacPHERSON,	
FRANKLIN & FRIEL LLP	7. Total fee (37 CFR 3.41):\$40.00
Street Address: 25 METRO DRIVE, SUITE 700	⊠ Authorized to be charged to Deposit Account 19-2386
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Statement and signature.	
To the best of my knowledge and belief, the foregoing information of the original document.	on is true and correct and any attached copy is a true copy
Posid T Millow	ind Millere 6-1-99
David T. Millers 37,396 Name of Person Signing	Signature Date
	Total number of pages comprising cover sheet: 1
	. c.c

PATENT REEL: 010005 FRAME: 0041

Atty. Docket No.: AB-697 US

ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, I, Hideki Horii of 102-1206, Shinbanpo Apt., 319-6, Ingye-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, hereby sell, assign and transfer to Samsung Electronics Co., Ltd., a Korean corporation, having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in my invention in

Capacitor Having Electrode Formed By Electroplating And Manufacturing Method Thereof

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the abovenamed assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

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Executed this 13 day of	April	, 19 77 .	
		Hidehi Horid	
		Hideki Horii	
WITNESSED:			
Signature			
Date			
Type or print name of witness			

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RECORDED: 06/01/1999

PATENT REEL: 010005 FRAME: 0042